

MetaMotionR

Wearable and connected devices product solution

Product Specification v0.5

Key Features

- Nordic Semiconductor nRF52832 BLE SoC
 - 2.4 GHz transceiver
 - ARM® Cortex™-M4F 32 bit processor
 - 512 kB flash program memory
 - 64 kB RAM
- Winbond W25Q64FV 64Mbit NOR Flash Extended Log Memory
- Bosch® BMI160 6-Axis Accelerometer/Gyroscope
 - $\pm 2g/\pm 4g/\pm 8g/\pm 16g$ selectable scale
 - 125/250/500/1000/2000 degrees/sec
 - Industry Leading 900uA active current gyro
- Bosch® BMM150 3-Axis Magnetometer
- Bosch® BMP280 Digital Pressure Sensor
 - 30 to 110 kPa range
 - 0.16 Pa resolution
- Lite-On® LTR-329ALS-01 Ambient Light Sensor
 - 0.01 to 64k lux range
- Firmware-enabled 9-axis sensor fusion
- Lithium Ion/Polymer battery charger
- Micro-USB rechargeable
- Bright RGB LED
- Miniature push-button switch
- High current / haptic driver
- Accurate Thermistor Temperature Sensor
- I/O Expansion
 - Digital I²C Bus
 - 4 Analog/Digital Pins
 - 3 Digital Pins
- Tiny 26mm x 17mm x 2.5mm form factor
- Form factor compatible with MetaWearRG/RPro
- FCC, IC, CE, Telec certification

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1 Introduction

MetaMotionR is a complete development and production platform for wearable and connected device applications. It features the ultra-low power nRF52832 SoC, providing energy efficient smartphone communication and central processing. MetaMotionR integrates this radio with high value sensors and a rechargeable battery architecture into a miniature form factor. All circuits have been designed from the ground up with energy efficiency in mind.

2 Product Overview

2.1 Block Diagram

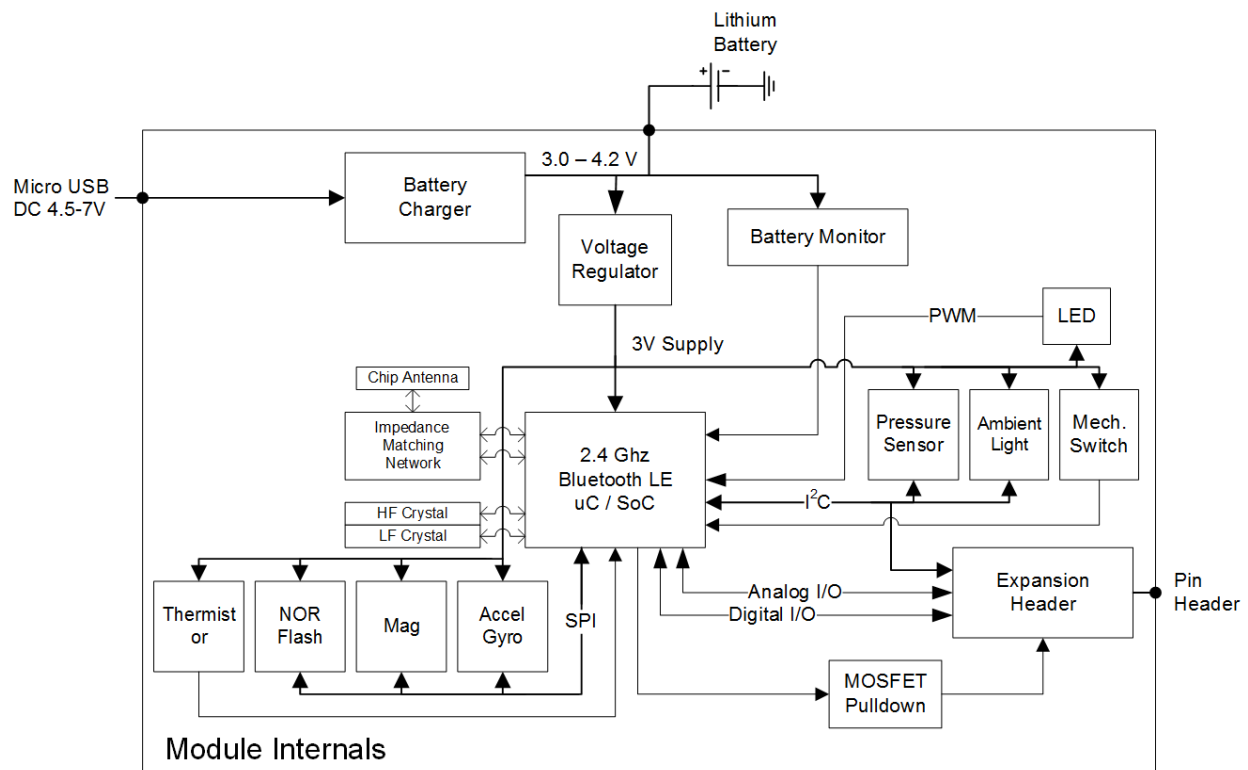


Figure 1 Block Diagram

2.2 Pin Assignments

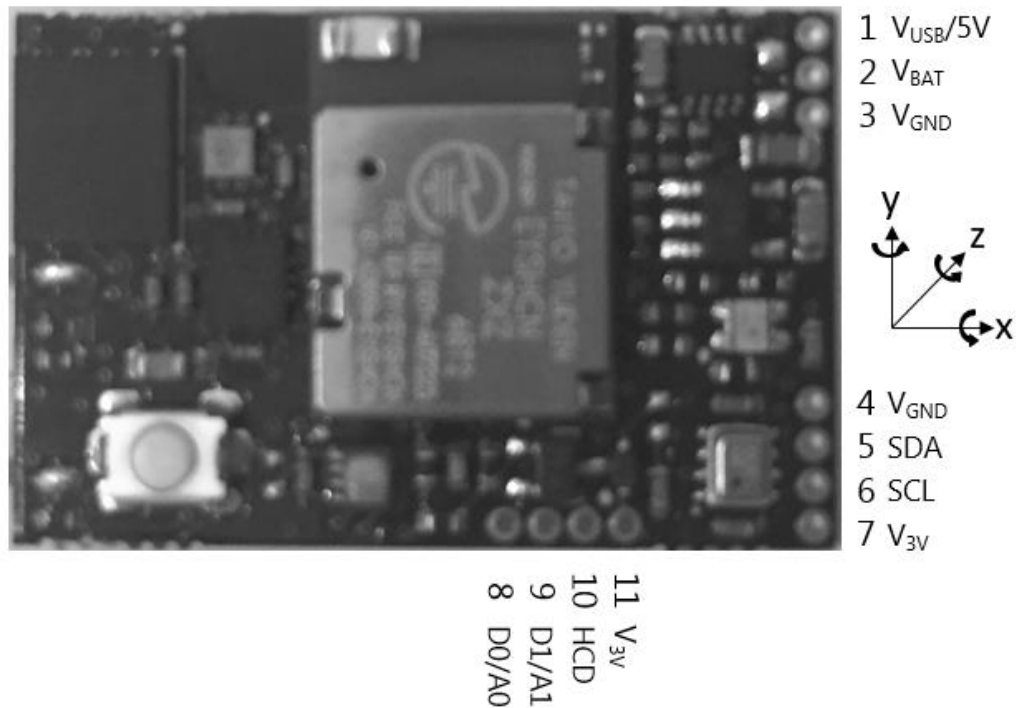


Figure 2 Front Pin Assignments

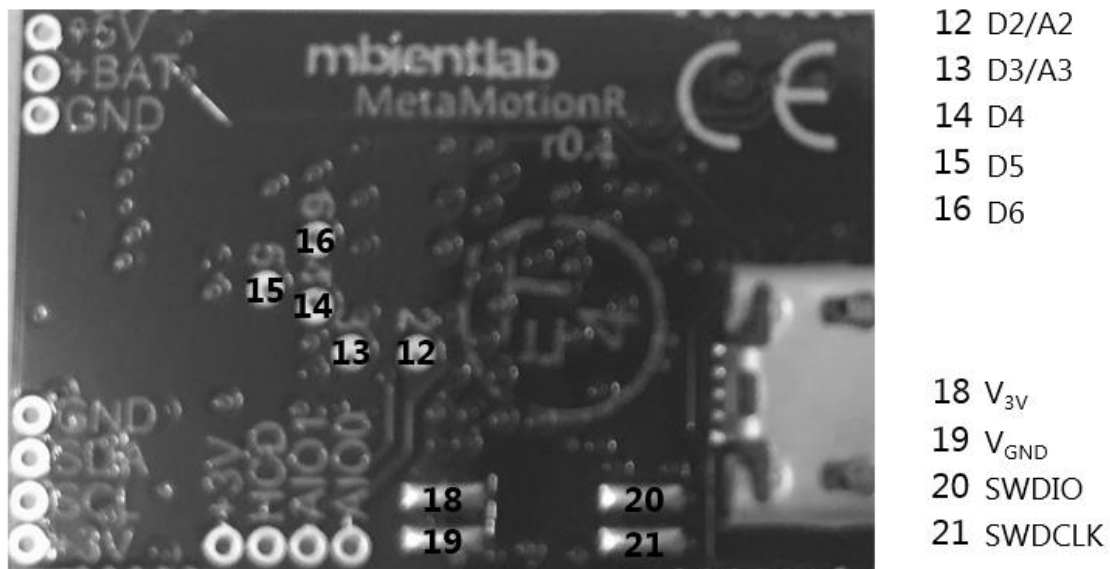


Figure 3 Back Pin Assignments

2.3 Pin Functions

Pin	Pin Name	Function	Description
Power Supply			
1	V _{USB}	Power	Positive supply alternative to micro USB port.
2	V _{BAT}	Power	Positive battery connection.
3	V _{GND}	Power	Ground connection intended for battery.
Digital Peripheral Bus			
4	V _{GND}	Power	Supplementary ground for peripheral expansion.
5	SDA	Digital I/O	I ² C serial data.
6	SCL	Digital I/O	I ² C serial clock.
7	V _{3V}	Power	Regulated 3V output for peripheral expansion.
Analog / High Current Driver Bus			
8	D0	Digital I/O	General purpose I/O and analog input.
	A0	Analog I/O	
9	D1	Digital I/O	General purpose I/O and analog input.
	A1	Analog I/O	
10	HCD	High Current Driver	Switch for sinking high current peripherals.
11	V _{3V}	Power	Regulated 3V output for high current peripheral.
Surface Mount Extra Breakout			
12	D2	Digital I/O	General purpose I/O and analog input.
	A2	Analog I/O	
13	D3	Digital I/O	General purpose I/O and analog input.
	A3	Analog I/O	
14	D4	Digital I/O	General purpose I/O.
15	D5	Digital I/O	General purpose I/O.
16	D6	Digital I/O	General purpose I/O.
SWD Debug Header			
18	V _{3V}	Power	System supply for debugger.
19	V _{GND}	Power	System ground for debugger.
20	SWDIO/nRESET	Debug	SWD debugger I/O line and system reset.
21	SWDCLK	Debug	SWD debugger clock line.

Table 1 Pin Functions

2.4 Module to SoC Pin Mapping

Module Pin	nF52832 Pin	Function	Description
GPIO			
D0/A0	P0.30	GPIO	General purpose I/O and analog input.
D1/A1	P0.02	GPIO	General purpose I/O and analog input.
D2/A2	P0.31	GPIO	General purpose I/O and analog input.
D3/A3	P0.03	GPIO	General purpose I/O and analog input.
D4	P0.15	GPIO	General purpose I/O.
D5	P0.17	GPIO	General purpose I/O.
D6	P0.19	GPIO	General purpose I/O.
High Current/Haptic Driver			
HCD	P0.10	Haptic	Open drain MOSFET pull-down.
I2C			
SDA	P0.11	Serial Bus	I ² C serial data.
SCL	P0.12	Serial Bus	I ² C serial clock.
Internal Module Pins			
	P0.07	Switch	Micro Push Button. Active Low.
	P0.21	5V Present	Active high indicator of an attached power source.
	P0.28	Battery Voltage	Analog voltage at V _{BAT} *(10.0/14.02)
	P0.16	Battery Charging	Open drain, active low indicator that the charger is active.
	P0.08	Thermistor En	Active High Enable for Thermistor
	P0.29	Themistor Voltage	Voltage output from Thermistor Voltage Divider
	P0.25	Acc/Gyro Interrupt	INT1 Pin of BMI160.
	P0.06	Acc/Gyro Interrupt	INT2 Pin of BMI160.
	P0.04	Acc/Gyro SCK	SCK Pin of BMI160, BMM150, W25Q64FV.
	P0.26	Acc/Gyro MISO	MISO Pin of BMI160, BMM150, W25Q64FV.
	P0.27	Acc/Gyro MOSI	MOSI Pin of BMI160, BMM150, W25Q64FV.
	P0.05	Acc/Gyro nCS	nCS Pin of BMI160.
	P0.22	Mag Interrupt	INT Pin of BMM150.
	P0.24	Mag Data Ready	DRDY Pin of BMM150.
	P0.23	Mag nCS	nCS Pin of BMM150
	P0.20	NOR Flash nCS	nCS Pin of W25Q64FV.
	P0.09	NOR Flash nWP	nWP Pin of W25Q64FV.
	P0.14	LED Red nEn	Current Sink for Red LED Channel.
	P0.18	LED Green nEn	Current Sink for Green LED Channel.
	P0.13	LED Blue nEn	Current Sink for Blue LED Channel.

Table 2 Module Pin Mapping

3 Circuit and Sensor Details

3.1 High Current/Haptic Drive Circuit

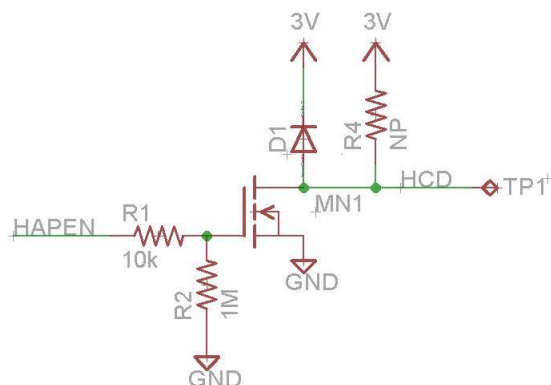


Figure 4 Haptic Driver Circuit

The haptic drive circuit features a logic level gate drive N-Channel MOSFET, and a flyback diode to 3V for switching inductive loads.

3.2 NOR Flash

The NOR Flash W25Q64FV is attached to the shared SPI bus, with dedicated nCS and nWP pins as detailed in the SoC mapping table.

3.3 Humidity / Barometric Pressure Sensor

The Barometric Pressure Sensor BMP280 or the Humidity and Barometric Pressure Sensor BME280 is attached to the shared I²C bus at slave address 0x77.

3.4 Accelerometer / Gyroscope

The 6-axis accelerometer and gyroscope sensor BMI160 attached via the SPI bus, with pin numbers detailed in the module to SoC mapping table.

3.5 Magnetometer

The 3-axis magnetometer BMM150 is attached via the SPI bus, with pin numbers detailed in the module to SoC mapping table.

3.6 Ambient Light Sensor

The Ambient Light Sensor LTR-329ALS-01 is attached to the shared I²C bus at slave address 0x29.

3.7 Mechanical Switch

The GPIO internal pullup resistor should be used with the mechanical switch, which is active low.

3.8 Thermistor Temperature Circuit

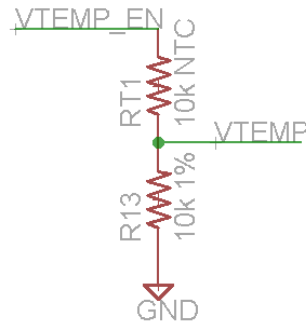


Figure 5 Thermistor Temperature Circuit

The thermistor circuit features a voltage divider and active high enable for power saving. Details on the sensor characteristics can be found in the data sheet for part number NCP15XH103F03RC.

3.9 RGB LED Circuit

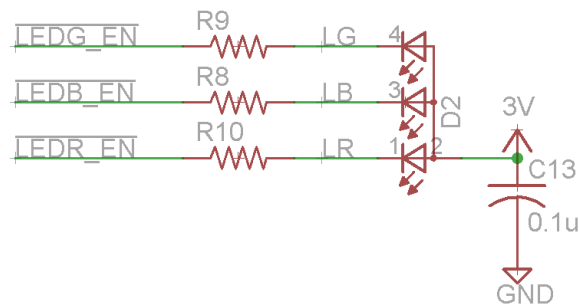


Figure 6 RGB LED Circuit

The RGB LED channels are driven by an active low PWM signal from the SoC. The resistance values have been chosen to approximately match intensity at 100 percent duty cycle. The high current bit should be set on the GPIOs to sink up to 5mA.

4 Absolute Maximum Ratings

Spec	Description	Min.	Typ.	Max.	Units
V _{USB}	USB charging voltage.	-0.3		+8.0	V
V _{BAT}	Lithium battery voltage.	-0.3		+6.0	V
V _{GND}	Ground voltage			0	V
V _{IO}	I/O Pin Voltage	-0.3		+3.3	V
T _{MAX}	Storage Temperature	-40		125	°C

Table 3 Absolute Maximum Ratings

5 Operating Conditions

Spec	Description	Min.	Typ.	Max.	Units
V _{USB}	USB charging voltage.	4.0	5.0	7.5	V
V _{BAT}	Lithium battery voltage.	3.0	3.7	4.2	V
T _A	Operating temperature.	-40	25	85	°C
I _{IDLE}	Idle current consumption.		20	50	uA

Table 4 Operating Conditions

6 Electrical Specifications

6.1 General Purpose I/O (GPIO) Specifications

Spec	Description	Min.	Typ.	Max.	Units
V _{IH}	Input high voltage.	2.1		3.0	V
V _{IL}	Input low voltage.	0		0.9	V
V _{OH}	Output high voltage.	2.6		3.0	V
V _{OL}	Output low voltage.	0		0.4	V
R _{PU}	Pull-up resistance.	11	13	16	kΩ
R _{PD}	Pull-down resistance.	11	13	16	kΩ

Table 5 General Purpose I/O (GPIO) Specifications

6.2 Crystal Oscillator Specifications (OSC)

Spec	Description	Min.	Typ.	Max.	Units
f _{HF,NOM}	High frequency crystal frequency		32		MHz
f _{HF,TOL}	High frequency crystal tolerance		±40		ppm
f _{LF,NOM}	Low frequency crystal frequency		32.768		kHz
f _{LF,TOL}	Low frequency crystal tolerance		±50		ppm

Table 6 Crystal Oscillator Specifications

6.3 SAADC (ADC) Specifications

Spec	Description	Min.	Typ.	Max.	Units
DNL _{10b}	Differential non-linearity (10 bit mode).		<1		LSB
INL _{10b}	Integral non-linearity (10 bit mode).		1		LSB
V _{OS}	Offset error.		±2		LSB
V _{REF_INT}	Internal reference voltage.	-3	0.6 V	+3	%
t _{ADC10b}	Sample conversion time.		<2		µs
t _{ACQ}	Sample acquisition time. Configurable.	3		40	µs
f _{MAX}	Maximum sampling rate.			200	kHz

Table 7 SAADC Specifications

6.4 Temperature Sensor (TEMP) Specifications

Spec	Description	Min.	Typ.	Max.	Units
T _{RANGE}	Temperature sensor range.	-40		85	°C
T _{ACC}	Temperature sensor accuracy.	-5		+5	°C
T _{RES}	Temperature sensor resolution.		0.25		°C
T _{THM_RANGE}	Thermistor sensor range.	-40		85	°C
T _{THM_ACC}	Thermistor sensor accuracy.	-1		+1	°C
T _{THM_RES}	Thermistor sensor resolution.		0.125		°C

Table 8 Temperature Sensor (TEMP) Specifications

6.5 High Current Driver (HCD) Specifications

Spec	Description	Min.	Typ.	Max.	Units
I _{ON,SS25}	Steady state on current at 25°C.			310	mA
I _{ON,SS85}	Steady state on current at 85°C.			220	mA
P _{ON,SS}	Steady state power dissipation.			280	mW
I _{ON,PULSE}	Pulsed current for 10 µs.			1.4	A
R _{ON}	On state resistance.		2	5	Ω
I _{OFF,LEAK}	Off state leakage.			1	nA
V _{CLAMP}	Clamping diode voltage threshold.		3.3		V

Table 9 High Current Driver (HCD) Specifications

6.6 Accelerometer (ACCEL) Specifications

Spec	Description	Min.	Typ.	Max.	Units
	Measurement range.	±2		±16	g
	Resolution.	2048		16384	counts/g
f _{DATA}	Data sample frequency.	0.78		1600	Hz
I _{12.5}	Low data rate current (3.125 Hz).		5		uA
I ₁₀₀	Mid data rate current (100 Hz).		24		uA
I ₁₆₀₀	High data rate current (1600 Hz).		180	300	uA
I _{STANDBY}	Standby current.		3	10	uA

Table 10 Accelerometer (ACCEL) Specifications

6.7 Gyroscope (GYRO) Specifications

Spec	Description	Min.	Typ.	Max.	Units
	Measurement range.	±125		±2000	°/s
	Resolution.	16		262	counts/°
f _{DATA}	Data sample frequency.	25		3200	Hz
I _{GYRO}	Gyro active current. All Data Rates.		850	900	uA
I _{STANDBY}	Standby current. Included in Accel Standby Current.				

Table 11 Gyroscope (GYRO) Specifications

6.8 Magnetometer (MAG) Specifications

Spec	Description	Min.	Typ.	Max.	Units
	Measurement range.	±1200	±1300		uT
	Heading Accuracy.			±2.5	°
f _{DATA}	Data rate.		25	300	Hz
I _{STANDBY}	Standby current.		1	3	uA

Table 12 Magnetometer (MAG) Specifications

6.9 Pressure (BAROMETER) Specifications

Spec	Description	Min.	Typ.	Max.	Units
	Measurement range.	30		110	kPa
	Resolution in ultra high resolution mode.		0.16		Pa
f_{DATA}	Data sample frequency at max data rate.			157	Hz
I_{ACTIVE}	Active current. Data rate and oversampling sensitive.	0.14		650	μA
$I_{STANDBY}$	Standby current.		0.1	0.3	μA
I_{PEAK}	Peak current during measurement.		720	1120	μA

Table 13 Pressure (BAROMETER) Specifications

6.10 LED (LED) Specifications

Spec	Description	Min.	Typ.	Max.	Units
I_{RGB}	Drive current per channel.	2	4	5	mA
λ_{RPEAK}	Red peak wavelength.		624		nm
λ_{GPEAK}	Green peak wavelength.		525		nm
λ_{BPEAK}	Blue peak wavelength.		470		nm
I_{VR}	Red luminous intensity.	12	60		mcd
I_{VG}	Green luminous intensity.	15	60		mcd
I_{VB}	Blue luminous intensity.	10	60		mcd
	Viewing Angle		120		°

Table 14 LED (LED) Specifications

6.11 Ambient Light (ALS) Specifications

Spec	Description	Min.	Typ.	Max.	Units
	Measurement range.	0.01		64k	lux
	Resolution.		16		bit
f_{DATA}	Data sample frequency.	0.5		20	Hz
I_{PEAK}	Peak active current.			220	μA
$I_{STANDBY}$	Standby current.			5	μA

Table 15 Ambient Light (ALS) Specifications

6.12 NOR Flash (NOR) Specifications

Spec	Description	Min.	Typ.	Max.	Units
	Powerdown current.		1	25	uA
	Write cycles per sector.	100,000			cycles
	Data retention	20			years
I _{READ}	Read current.			10	mA
I _{PROGRAM}	Program current.		20	25	mA
I _{ERASE}	Erase current.		20	25	mA
t _{SSE}	Subsector Erase time.		60	400	ms
t _{CE}	Chip Erase time.		20	100	s

Table 16 NOR Flash (NOR) Specifications

6.13 Sensor Fusion (SF) Specifications

Spec	Description	Min.	Typ.	Max.	Units
f _{NDOF}	NDoF operating frequency.	-1%	100	+1%	Hz
f _{IMUPLUS}	IMUPlus operating frequency.	-1%	100	+1%	Hz
f _{COMPASS}	Compass operating frequency.	-1%	25	+1%	Hz
f _{M4G}	M4G operating frequency.	-1%	50	+1%	Hz

Table 17 Sensor Fusion (SF) Specifications

7 Mechanical Specifications

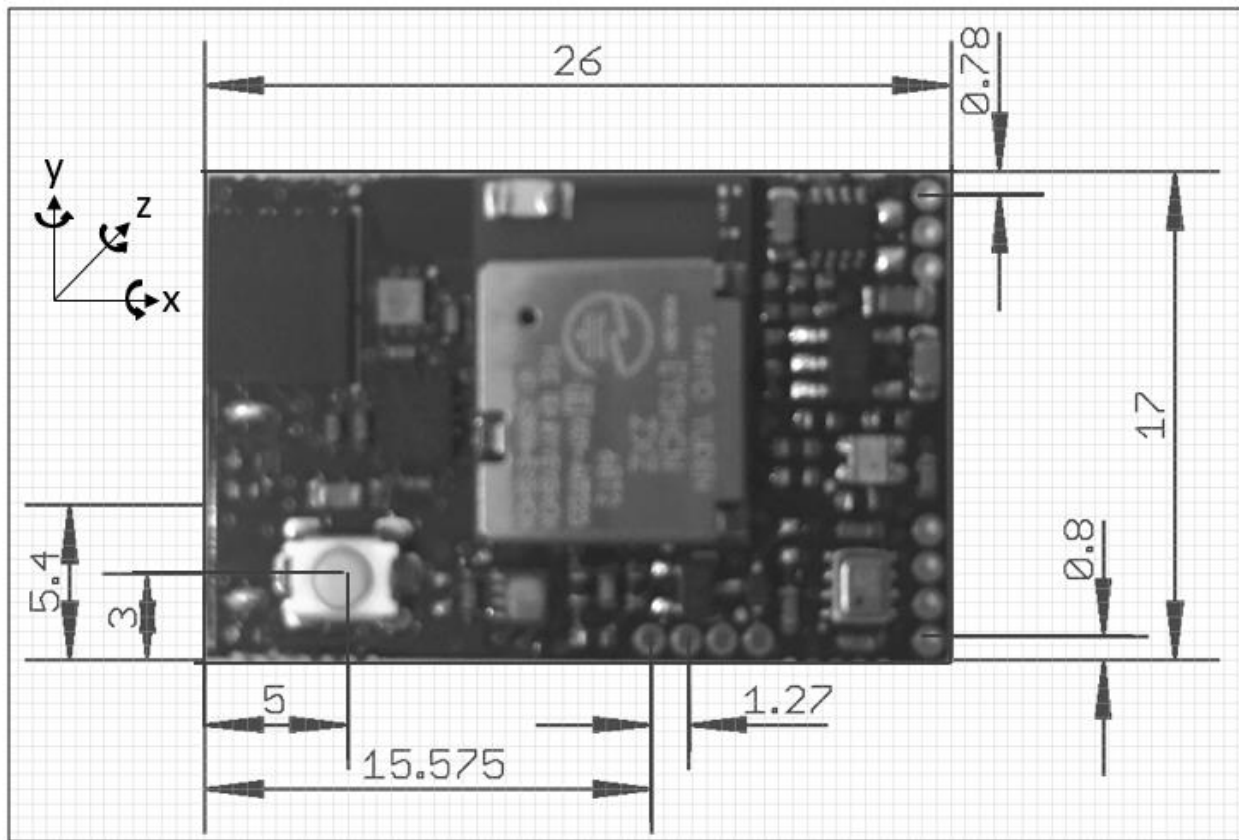


Figure 7 Module dimensions in mm

9 Revision History

Date	Version	Change Description
November 21, 2016	0.5	Initial Draft

Table 18 *Revision History*

10 Regulatory Information for MetaMotionR

10.1 Taiyo Yuden Radio Module Approval

The MetaMotionR uses the Taiyo Yuden module, part number EYSHCNZXZ. The module is Bluetooth qualified, Telec (Japan), FCC, and IC (Canada) certified.

- Datasheet: http://www.yuden.co.jp/wireless_module/document/overview/TY_BLE_Overview_V1_3_20160809.pdf
- Bluetooth Listing: https://www.bluetooth.org/tpg/QLI_viewQDL.cfm?qid=30114
- IC: <https://industrycanada.co/number.php?ic=4389B-EYSFCN&id=171601>
- FCC: <https://fccid.io/RYYEYSHCN>

10.2 CE Conformance

The MetaMotionR boards are conformant to relevant CE specifications.

- Details: <https://mbientlab.com/docs/MetaWearDeclarationOfConformity.pdf>

10.3 FCC Labeling Requirements

If the FCC ID is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording such as the following: “Contains Transmitter Module FCC ID: RYY-EYSHCN” or “Contains FCC ID: RYY-EYSHCN”. Any similar wording that expresses the same meaning may be used.

10.4 IC Labeling Requirements

Labeling requirements for Industry Canada are similar to those required by the FCC. A clearly visible label on the outside of a non-removable part of the final product must include the following text: "Contains IC: 4389B-EYSHCN".

Les exigences d'étiquetage pour l'Industrie Canada sont semblables à ceux exigés par la FCC. Une étiquette bien visible à l'extérieur d'une partie non amovible du produit doit inclure le texte suivant: "Contains IC: 4389B-EYSHCN".